CLAIMS

1. A magnetic head comprising:

a substrate;

a read head being fabricated upon said substrate;

a P1 pole being fabricated upon said read head;

a write gap layer being fabricated upon said P1 pole;

a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole tip includes a first portion being comprised of a seed layer material and a second portion being comprised of electroplated material, and wherein said P2 pole tip has a width dimension W that is formed in part from a thickness of said seed layer material portion and in part from a thickness of said electroplated material portion.

2. A magnetic head as described in claim 1 wherein said first portion of said P2 pole tip that is comprised of said seed layer material forms a sidewall of said P2 pole tip.

3. A magnetic head as described in claim 1 wherein said seed layer material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said electroplated material is formed with a thickness of approximately 100 Å to approximately 5000 Å.

4. A magnetic head as described in claim 3 wherein said seed layer material thickness is approximately 250 Å and said electroplated material thickness is approximately 1500 Å.

5. A magnetic head as described in claim 3 wherein said seed layer material is comprised of NiFe and said electroplated material is comprised of NiFe.

6. A hard disk drive comprising:

at least one hard disk being fabricated for rotary motion upon a disk drive;

at least one magnetic head adapted to fly over said hard disk for writing data on said hard disk, said magnetic head including:

a substrate;

a read head being fabricated upon said substrate;

a P1 pole being fabricated upon said read head;

a write gap layer being fabricated upon said P1 pole;

a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole tip includes a first portion being comprised of a seed layer material and a second portion being comprised of electroplated material, and wherein said P2 pole tip has a width dimension W that is formed in part from a thickness of said seed layer material portion and in part from a thickness of said electroplated material portion.

7. A hard disk drive as described in claim 6 wherein said first portion of said P2 pole tip that is comprised of said seed layer material forms a sidewall of said P2 pole tip.

8. A hard disk drive as described in claim 6 wherein said seed layer material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said electroplated material is formed with a thickness of approximately 100 Å to approximately 5000 Å.

9. A hard disk drive as described in claim 8 wherein said seed layer material thickness is approximately 250 Å and said electroplated material thickness is approximately 1500 Å.

10. A hard disk drive as described in claim 8 wherein said seed layer material is comprised of NiFe and said electroplated material is comprised of NiFe.

11. A method for fabricating a magnetic head, comprising the steps of:

fabricating a read head upon a substrate;

fabricating a P1 pole upon said read head;

fabricating a write gap layer upon said P1 pole;

fabricating a block of material upon said write gap layer, said block of material having a sidewall disposed proximate a P2 pole tip location;

fabricating a seed layer upon said sidewall;

electroplating P2 pole tip material upon said seed layer, whereby a P2 pole tip is formed having a width W that is comprised of a thickness of said seed layer material and a thickness of said electroplated material;

fabricating an induction coil proximate said P2 pole tip;

fabricating a P3 pole above said induction coil in magnetic interconnection with said P2 pole tip; and

fabricating an encapsulation layer above said P3 pole.

12. A method for fabricating a magnetic head as described in claim 11 wherein said seed layer is fabricated to a thickness of approximately 50 Å to approximately 500 Å.

13. A method for fabricating a magnetic head as described in claim 11 wherein said electroplated material is fabricated to a thickness of approximately 100 Å to approximately 5000 Å.

14. A method for fabricating a magnetic head as described in claim 11 wherein said seed layer is fabricated to a thickness of approximately 50 Å to approximately 500 Å, and wherein said electroplated material is fabricated to a thickness of approximately 100 Å to approximately 5000 Å.

15. A method for fabricating a magnetic head as described in claim 14 wherein said seed layer is fabricated to a thickness of approximately 250 Å and said electroplated material is fabricated to a thickness of approximately 1500 Å.

16. A method for fabricating a magnetic head as described in claim 11 wherein said P2 pole tip is fabricated within a P2 pole tip trench having width that is wider than said width W of said P2 pole tip.

17. A method for fabricating a magnetic head as described in claim 11 wherein said block of material is removed from said write gap layer following said electroplating of said P2 pole tip material, and said P1 pole is notched in an ion milling step.

18. A method for fabricating a magnetic head as described in claim 14, wherein said seed layer is comprised of NiFe and said P2 pole tip material that is electroplated upon said seed layer is comprised of NiFe.